

BCR30AM-12LA

Triac

Medium Power Use

REJ03G0342-0300

Rev.3.00

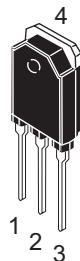
Nov 30, 2007

Features

- $I_{T(RMS)}$: 30 A
- V_{DRM} : 600 V
- $I_{FGT I}$, $I_{RGT I}$, $I_{RGT III}$: 50 mA
- Non-Insulated Type
- Planar Passivation Type

Outline

RENESAS Package code: PRSS0004ZE-A
(Package name: TO-3P)



1. T₁ Terminal
2. T₂ Terminal
3. Gate Terminal
4. T₂ Terminal

Applications

Contactless AC switch, electric heater control, light dimmer, on/off and speed control of small induction motor, on/off control of copier lamp

Maximum Ratings

Parameter	Symbol	Voltage class	Unit
		12	
Repetitive peak off-state voltage ^{Note1}	V_{DRM}	600	V
Non-repetitive peak off-state voltage ^{Note1}	V_{DSM}	720	V

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_{T(RMS)}$	30	A	Commercial frequency, sine full wave, $T_c = 75^\circ\text{C}$
Surge on-state current	I_{TSM}	300	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
I^2t for fusing	I^2t	378	A^2s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	P_{GM}	5	W	
Average gate power dissipation	$P_{G(AV)}$	0.5	W	
Peak gate voltage	V_{GM}	10	V	
Peak gate current	I_{GM}	2	A	
Junction temperature	T_j	- 40 to +125	$^\circ\text{C}$	
Storage temperature	T_{stg}	- 40 to +125	$^\circ\text{C}$	
Mass	—	4.8	g	Typical value

Notes: 1. Gate open.

Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Repetitive peak off-state current	I_{DRM}	—	—	3.0	mA	$T_j = 125^\circ\text{C}$, V_{DRM} applied
On-state voltage	V_{TM}	—	—	1.6	V	$T_c = 25^\circ\text{C}$, $I_{TM} = 45\text{A}$
Gate trigger voltage ^{Note2}	I	V_{FGTI}	—	—	2.5	$T_j = 25^\circ\text{C}$, $V_D = 6\text{V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$
	II	V_{RGTI}	—	—	2.5	
	III	V_{RGTIII}	—	—	2.5	
Gate trigger current ^{Note2}	I	I_{FGTI}	—	—	50	$T_j = 25^\circ\text{C}$, $V_D = 6\text{V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$
	II	I_{RGTI}	—	—	50	
	III	I_{RGTIII}	—	—	50	
Gate non-trigger voltage	V_{GD}	0.2	—	—	V	$T_j = 125^\circ\text{C}$, $V_D = 1/2 V_{DRM}$
Thermal resistance	$R_{th(j-c)}$	—	—	1.2	$^\circ\text{C}/\text{W}$	Junction to case ^{Note3}
Critical-rate of rise of off-state commutating voltage ^{Note4}	$(dv/dt)_c$	20	—	—	$\text{V}/\mu\text{s}$	$T_j = 125^\circ\text{C}$

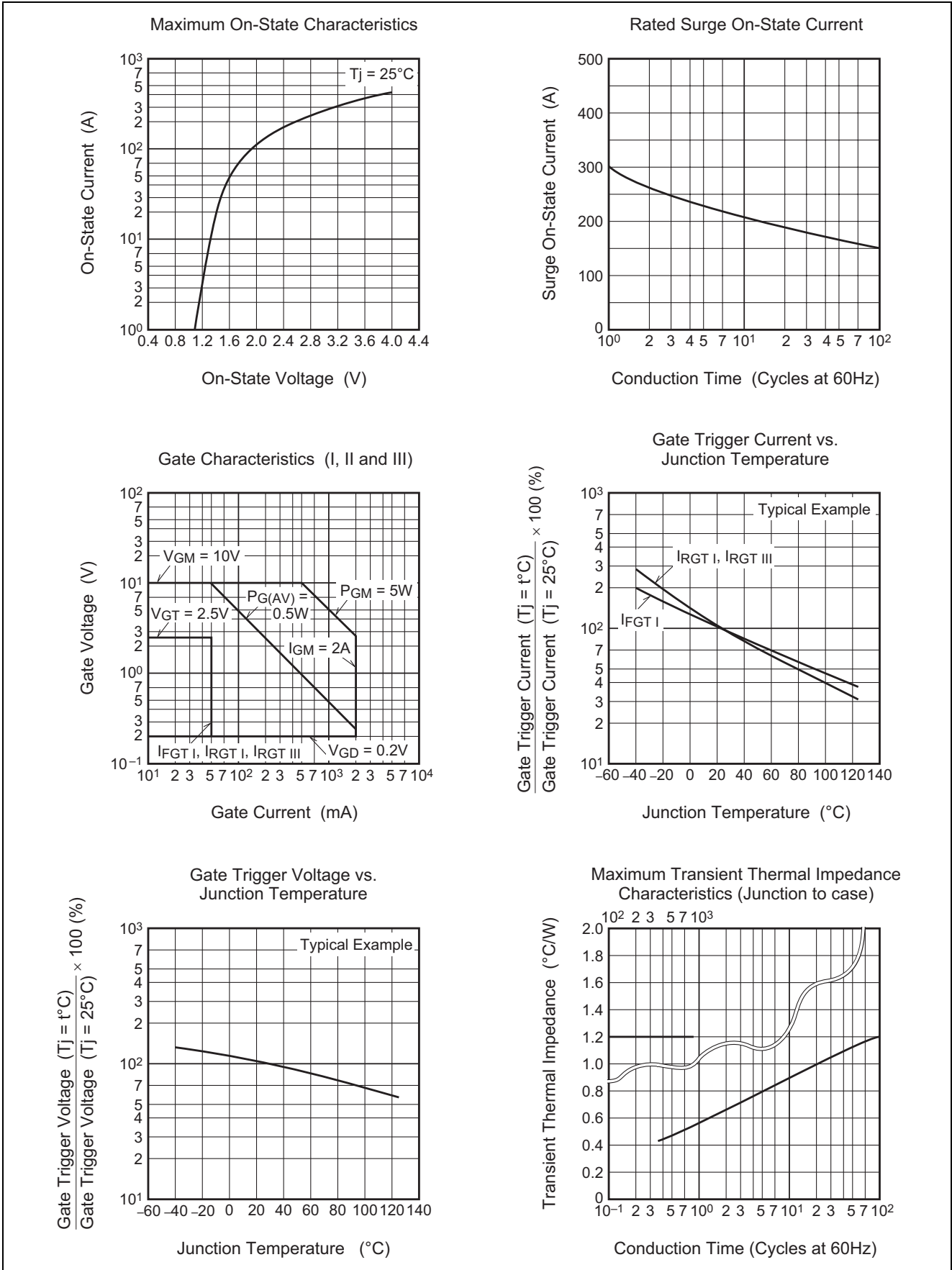
Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

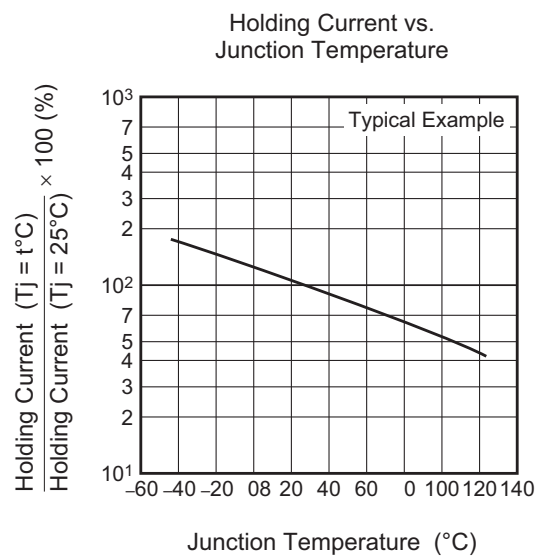
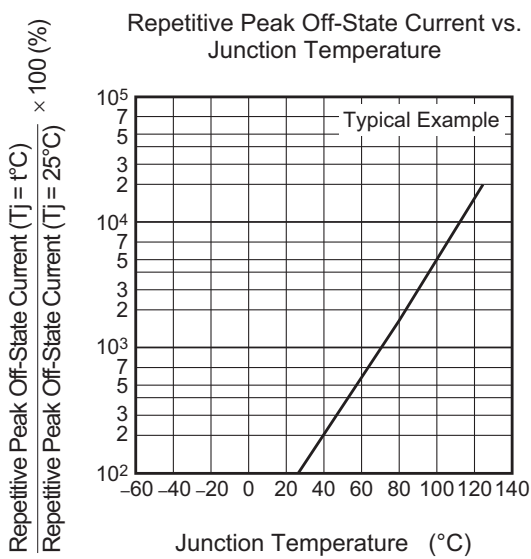
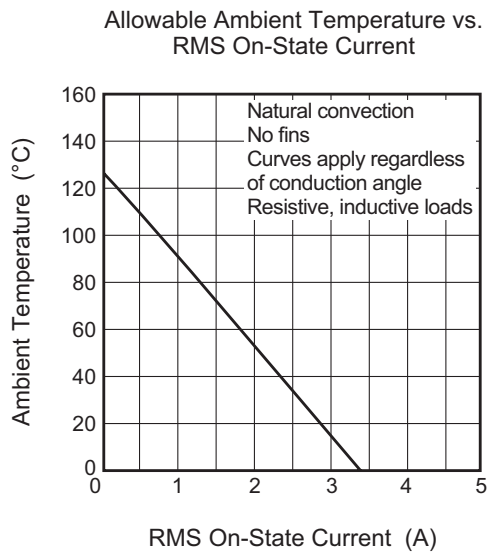
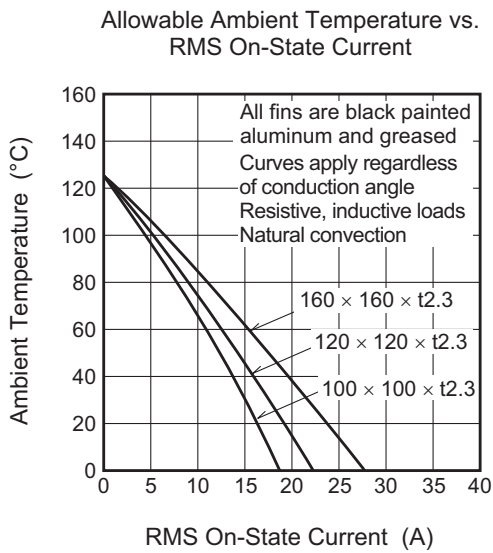
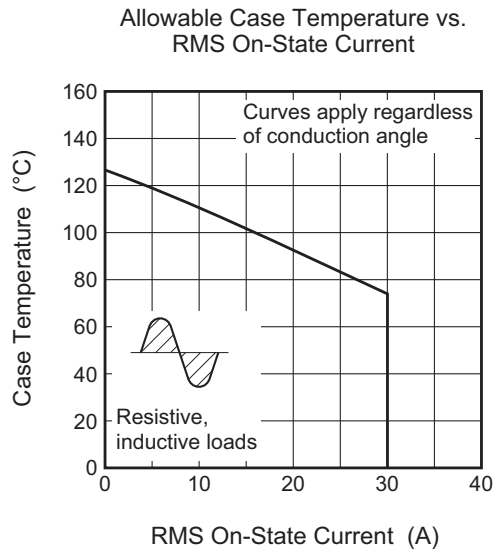
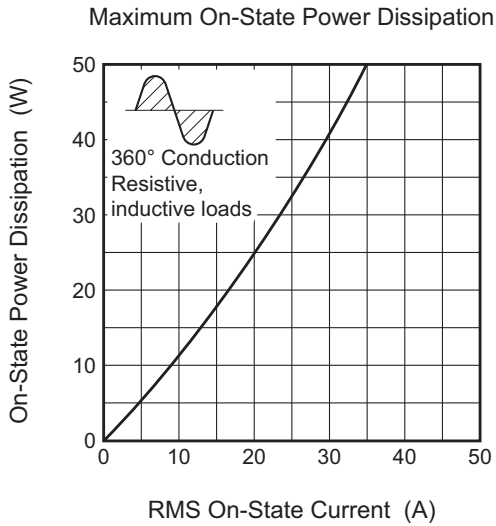
3. The contact thermal resistance $R_{th(c-f)}$ in case of greasing is $0.3^\circ\text{C}/\text{W}$.

4. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

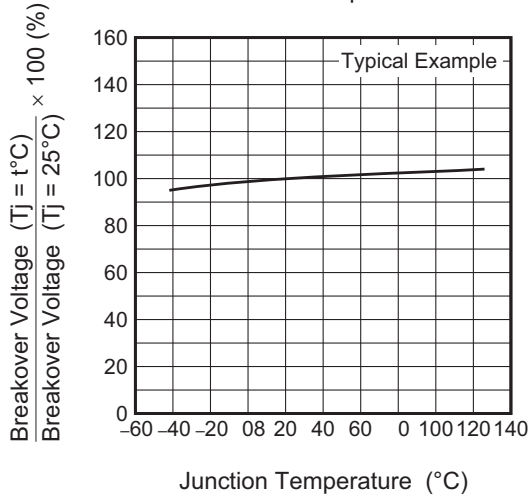
Test conditions	Commutating voltage and current waveforms inductive load
1. Junction temperature $T_j = 125^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_c = -16\text{A/ms}$ 3. Peak off-state voltage $V_D = 400\text{V}$	

Performance Curves

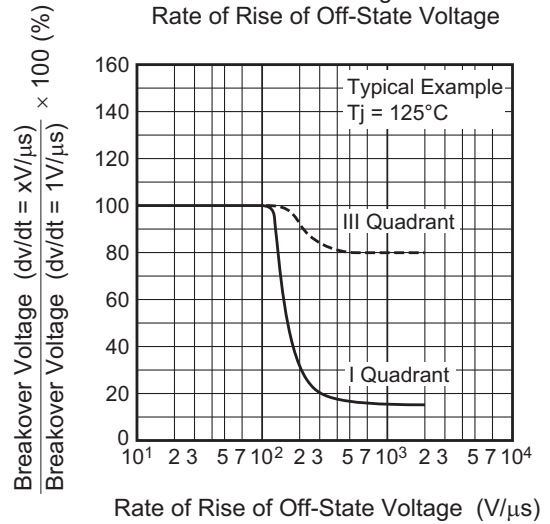




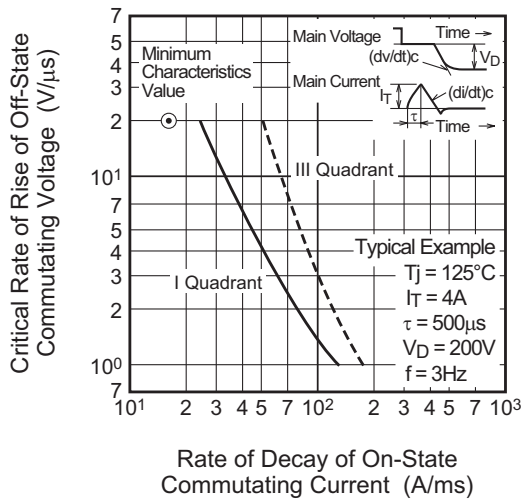
Breakover Voltage vs. Junction Temperature



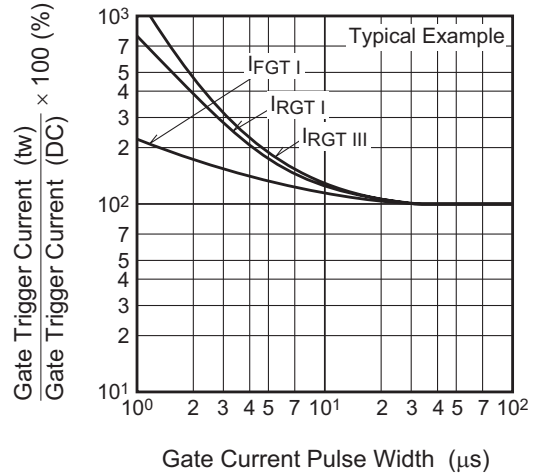
Breakover Voltage vs. Rate of Rise of Off-State Voltage



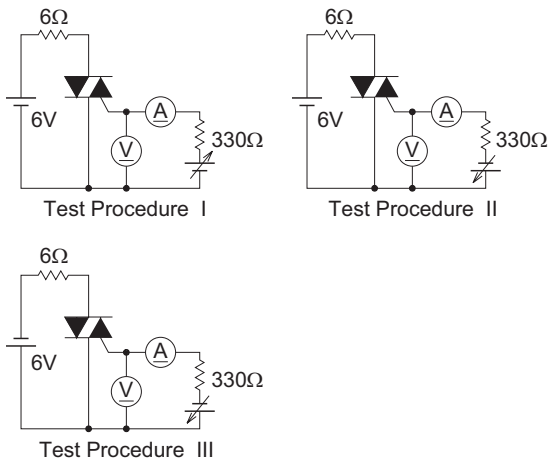
Commutation Characteristics



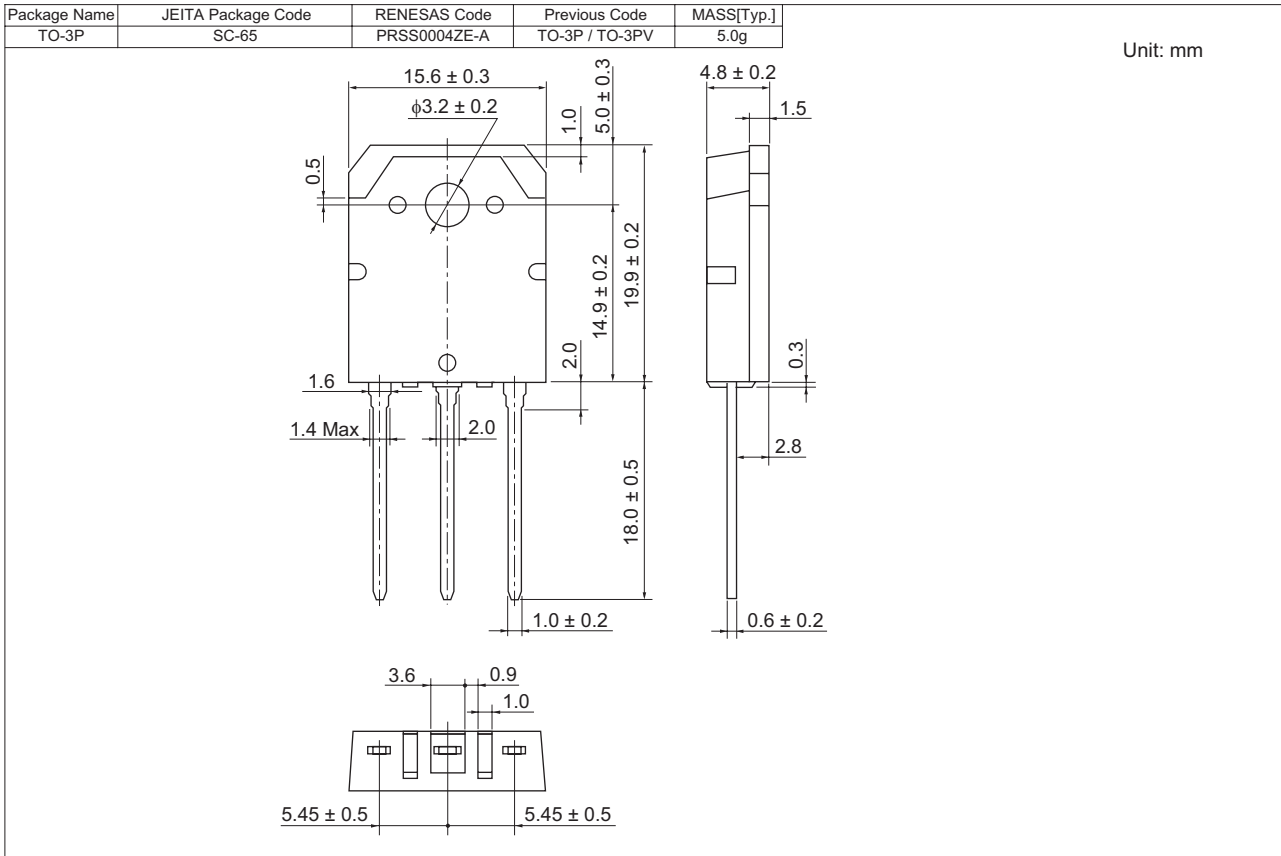
Gate Trigger Current vs. Gate Current Pulse Width



Gate Trigger Characteristics Test Circuits



Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	20	Type name	BCR30AM-12LA
Lead form	Plastic Magazine (Tube)	30	Type name – Lead forming code	BCR30AM-12LA-A8

Note : Please confirm the specification about the shipping in detail.

Notes:

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